

Title (en)
HOTSPOT SPRAY COOLING

Title (de)
HEISSSTELLEN-SPRITZKÜHLUNG

Title (fr)
REFROIDISSEMENT D'UN POINT CHAUD PAR PULVERISATION

Publication
EP 1754011 A2 20070221 (EN)

Application
EP 05722976 A 20050214

Priority
• US 2005004444 W 20050214
• US 78645204 A 20040224

Abstract (en)
[origin: US2005183844A1] The present invention is a spray cooling thermal management device that cools an electronic component creating a varying amount of heat across its surfaces. Liquid coolant is dispensed upon the surface of the component. In areas of the chip that generate large heat fluxes, typically referred to as the core, the liquid coolant is dispensed as a continuous atomized droplet pattern. The atomized pattern creates a high heat flux evaporative cooling thin-film over the one or more core areas. Rather than optimize the atomized pattern and flow based upon complete thin-film vaporization, the present invention optimizes the atomized pattern for maximum heat removal rates. Any excess, non-vaporized, fluid flowing outward from the hotspot is used to cool the lower heat flux (non-core) areas of the component through the creation of a thick coolant film thereon.

IPC 8 full level
F28F 7/00 (2006.01); **F28D 15/02** (2006.01); **H01L 23/473** (2006.01)

CPC (source: EP US)
F28D 15/0266 (2013.01 - EP US); **H01L 23/4735** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US)

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU MC NL PL PT RO SE SI SK TR

Designated extension state (EPC)
AL BA HR LV MK YU

DOCDB simple family (publication)
US 2005183844 A1 20050825; CA 2556666 A1 20050909; EP 1754011 A2 20070221; EP 1754011 A4 20090805; JP 2007538384 A 20071227; WO 2005081812 A2 20050909; WO 2005081812 A3 20070809

DOCDB simple family (application)
US 78645204 A 20040224; CA 2556666 A 20050214; EP 05722976 A 20050214; JP 2007500863 A 20050214; US 2005004444 W 20050214